

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	15APR22	R. WHITNEY
B	CHANGES AS PER ECR-109621	04OCT22	R. WHITNEY
C	CHANGES AS PER ECR-111941	27JAN23	R. WHITNEY
D	CHANGES AS PER ECR-113566	11APR23	R. WHITNEY
E	CHANGES AS PER ECR-115079	08AUG23	R. WHITNEY

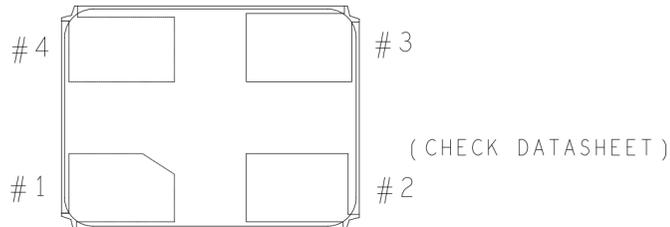
ASSEMBLY NOTES:

- BOARD ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00119 (LATEST REVISION).
- REPAIRS PER IPC-7711/21(LATEST REVISION) ARE ALLOWED.
- REPAIRS ARE NOT ALLOWED IN SOLDERMASK FREE AREAS ON EITHER SIDE OF THE BOARD.
- SEE DETAIL A FOR Y1 INSTALLATION.
- U9 IS A DEVICE-SOCKET COMBO AND FOLLOWS THIS SOLDERPASTE INSTRUCTION:

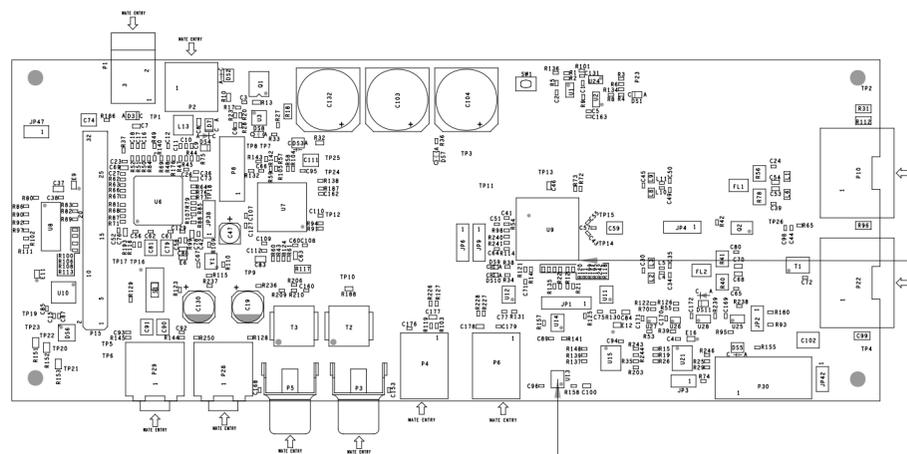
SUPPLIED PART	INSTALLED PART	PASTEMASK
U20(SOCKET)	INSTALLED SOCKET	NO PASTEMASK
U20(DEVICE)	INSTALLED DUT	PASTEMASK

- RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND ROHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).
- BOARD ASSEMBLY SPECIAL NOTES: (IN ORDER TO MINIMIZE MIC DEVICES (U11-U14) DAMAGE)
 - DO NOT BOARD WASH OR CLEAN AFTER THE REFLOW PROCESS.
 - DO NOT BRUSH BOARD WITH OR WITHOUT SOLVENTS AFTER THE REFLOW PROCESS.
 - DO NOT DIRECTLY EXPOSE TO ULTRASONIC PROCESSING, WELDING, OR CLEANING.
 - DO NOT INSERT ANY OBJECT IN PORT HOLE OF DEVICE AT ANY TIME.
 - DO NOT APPLY OVER 30 PSI OF AIR PRESSURE INTO THE PORT HOLE.
 - DO NOT PULL A VACUUM OVER PORT HOLE OF THE MICROPHONE.
 - DO NOT APPLY A VACUUM WHEN REPACKING INTO SEALED BAGS AT A RATE FASTER THAN 0.5 ATM/SEC.
- BOARDS TO BE SHIPPED SINGULATED AFTER ASSEMBLY PROCESS. SMOOTHEN EDGES AND FREE FROM BURRS AFTER DEPANELIZATION PROCESS.

Note: Actual device pin #1 has a chamfered corner terminal as shown.



DETAIL A FOR COMPONENT Y1

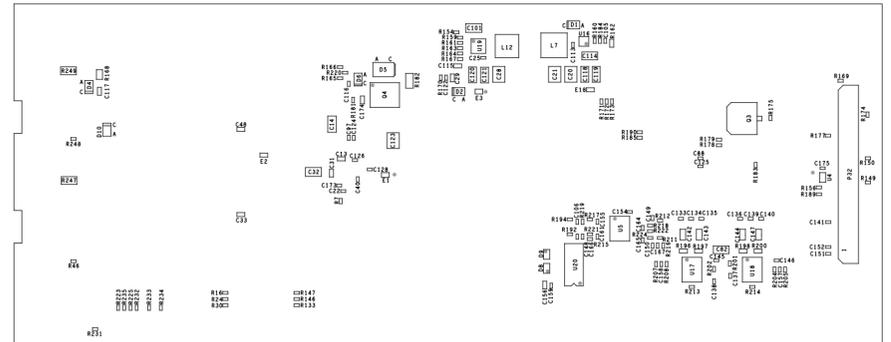
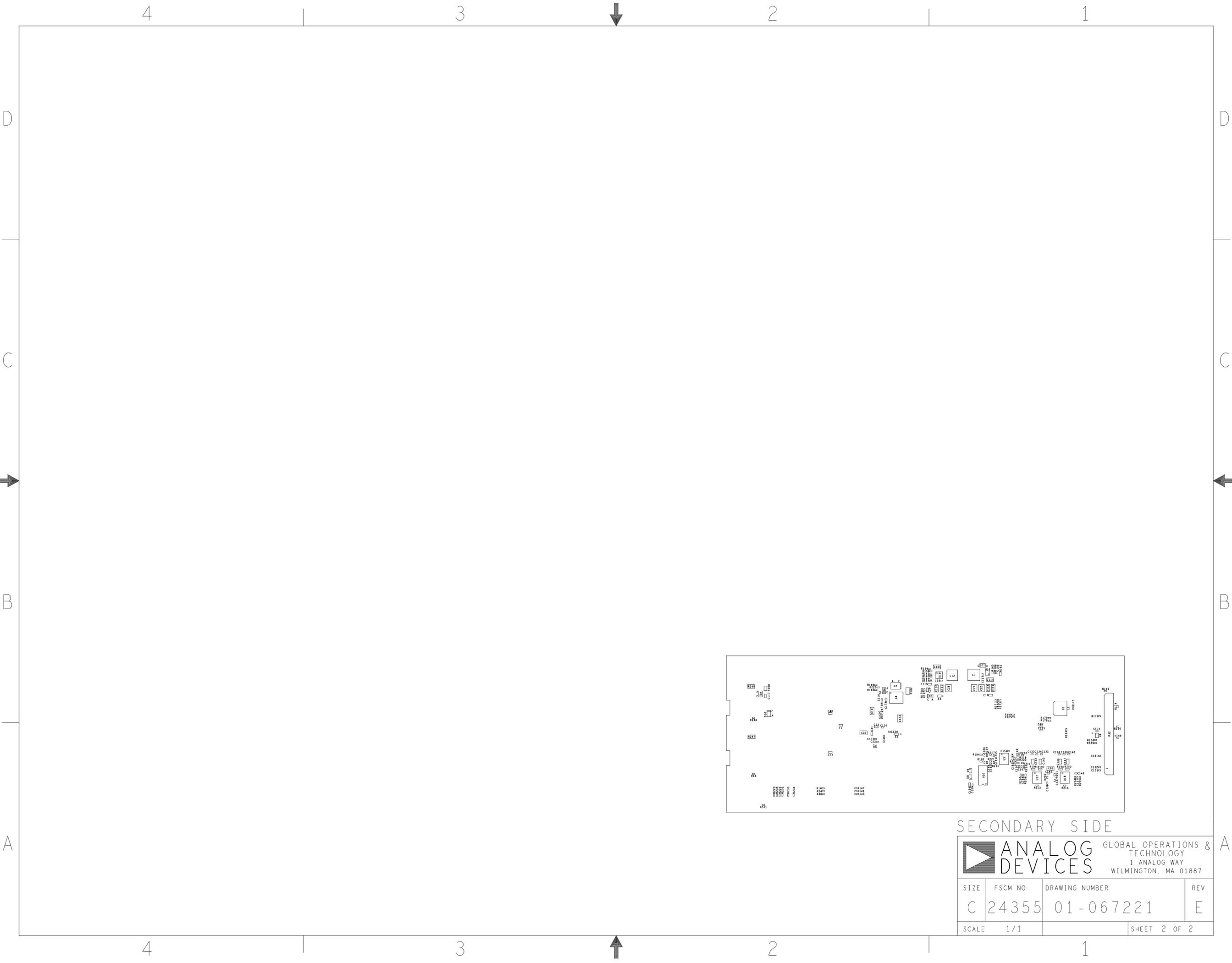


SEE ASSY NOTE #5

SEE NOTE 7 (4 PLACES)

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 --1/32 -- 2 .XXX -.005 .XXXX -.0050	APPROVAL	DATE	 GLOBAL OPERATIONS & TECHNOLOGY 1 ANALOG WAY WILMINGTON, MA 01887			
	TEMPLATE ENGINEER	03NOV21				
MATERIAL	TEST ENGINEER		TITLE ASSEMBLY EVAL-AD2437A1MZ_BRD CUSTOMER EVALUATION Z			
	COMPONENT ENGINEER M. YAN TEST PROCESS	03NOV21				
FINISH	HARDWARE RELEASE K. JABATAN	03NOV21	SIZE	FSCM NO	DRAWING NUMBER	REV
	DESIGNER R. PLANADA PTD ENGINEER R. WHITNEY CHECKER	15APR22	C	24355	01-067221	E
DO NOT SCALE DWG			SCALE	1/1		SHEET 1 OF 2



SECONDARY SIDE

ANALOG DEVICES GLOBAL OPERATIONS & TECHNOLOGY
 1 ANALOG WAY
 WILMINGTON, MA 01887

SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	01-067221	E
SCALE	1/1	SHEET 2 OF 2	